

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A circuit board manufacturing method, comprising:
~~_____ forming a transfer chip on a first substrate, the forming of the transfer chip including:~~
~~_____ forming a thin film line above the first substrate and forming a plurality of first pad electrodes so as to be connected to the thin film line, the thin film line and the first pad electrodes both being an integral part of the transfer chip,~~
_____ providing a transfer chip that has a first pad electrode that has a first part positioned at a highest level within the first pad electrode from a bottom of the transfer chip and a second electrode that has a second part positioned at a highest level within the second electrode from the bottom of the transfer chip, a thickness of the transfer chip at the first part being greater than a thickness of the transfer chip at the second part; and
joining the transfer chip with a member such that the ~~plurality of first pad electrodes~~first pad electrode and the second pad electrode contact the member.
2. (Currently Amended) The circuit board manufacturing method according to claim 1,~~each of the plurality of first pad electrodes having a plurality of first portions, one of the plurality of first portions being located a greatest vertical distance away from a bottom of the transfer chip, and the greatest distance substantially coinciding with the plurality of first pad electrodes.~~
_____ the member having a third pad electrode and a fourth pad electrode,
_____ the joining of the transfer chip being carried out such that the first pad electrode contacts the third pad electrode.

3. (Currently Amended) The circuit board manufacturing method according to ~~claim 1, further comprising:~~claim 2,

~~_____~~ the joining of the transfer chip being carried out such that the second pad electrode contacts the fourth pad electrode.

~~_____~~ forming the member, the forming of the member including:

~~_____~~ forming a second substrate, and

~~_____~~ forming electrical circuit wiring above the second substrate and a plurality of second pad electrodes so as to be connected to the electrical circuit wiring and arranged in a transfer target region, the second pad electrodes being respectively associated with the plurality of first pad electrodes provided on the transfer chip.

4. (Currently Amended) The circuit board manufacturing method according to ~~claim 2, further comprising:~~claim 1,

~~_____~~ the member having a third pad electrode that has a third part positioned at a highest level within the third pad electrode from a bottom of the member and a fourth electrode that has a fourth part positioned at a highest level within the fourth pad electrode from the bottom of the member, and

~~_____~~ a thickness of the transfer chip at the fourth part being greater than a thickness of the transfer chip at the third part.

~~_____~~ adjusting a distance of at least one of the plurality of first portions of each of the first pad electrodes from the bottom of the first substrate by adding distance-adjusting films when forming the transfer chip.

5. (Currently Amended) The circuit board manufacturing method according to ~~claim 3, forming the plurality of second pad electrodes so as to cover the electrical circuit wiring, each of the plurality of second pad electrodes having a plurality of second portions, one of the plurality of second portions being located a greatest distance away from a bottom~~

~~of the second substrate, the greatest distance substantially coinciding with the plurality of second pad electrodes.~~claim 4,

the joining of the transfer chip being carried out such that the first pad electrode and the second pad electrode contact the third pad electrode and the fourth pad electrode, respectively.

6. (Currently Amended) The circuit board manufacturing method according to ~~claim 5, further comprising:~~claim 1,

the first pad electrode further having a fifth part at which a thickness of the transfer chip is shorter than the thickness of the first part,

the first pad electrode further having a sixth part at which a thickness of the transfer chip is shorter than the thickness of the fifth part, and

the sixth part being positioned between the first part and the fifth part.

~~adjusting a distance of at least one of the plurality of second portions of each of the second pad electrodes from the bottom of the second substrate by adding distance adjusting films when forming the member.~~

7. (Currently Amended) The circuit board manufacturing method according to ~~claim 1, the plurality of first pad electrodes having a film structure that is the same as a film structure in regions associated with a greatest distance of a plurality of first portions of each of the first pad electrodes from a bottom of the transfer chip.~~claim 6,

the third pad electrode further having a seventh part at which a thickness of the member is shorter than the thickness at the third part,

the third pad electrode further having an eighth part at which a thickness of the member is shorter than the thickness at the seventh part, and

the eighth part being positioned between the third part and the seventh part.

8. (Currently Amended) The circuit board manufacturing method according to ~~claim 3, the plurality of second pad electrodes having a film structure that is the same as a film structure in regions associated with a greatest distance of a plurality of second portions of each of the second pad electrodes from a bottom of the second substrate.~~claim 7,
the first part contacting the third part.

9. (Currently Amended) The circuit board manufacturing method according to ~~claim 1, further comprising:~~claim 1,
the first pad electrode being formed on a first insulating film,
the first pad electrode further having a fifth part at which a thickness of the transfer chip is shorter than the thickness of the first part, and
a distance between the first insulating film and the first part being greater than a distance between the first insulating film and the fifth part.
~~connecting one first portion of a plurality of first portions of one first pad electrode of the plurality of first pad electrodes to one second portion of a plurality of second portions of one second pad electrode of a plurality of second pad electrodes; and~~
~~connecting one first portion of the plurality of first portions of another first pad electrode of the plurality of first pad electrodes to one second portion of the plurality of second portions of another second pad electrode of the plurality of second pad electrodes,~~
~~a distance between a bottom of the transfer chip and a bottom of the second substrate through the one first pad electrode and the one second pad electrode coinciding with a distance through the another first pad and the another second pad electrode.~~

10. (Currently Amended) The circuit board manufacturing method according to ~~claim 2, claim 3, the joining of the transfer chip with the member including forming adhesive layers between the first pad electrodes provided on the transfer chip and the second pad electrodes provided on the second substrate.~~

the first pad electrode further having a fifth part at which a thickness of the transfer chip is shorter than the thickness of the first part,

the first pad electrode further having a sixth part at which a thickness of the transfer chip is shorter than the thickness of the fifth part,

the sixth part being positioned between the first part and the fifth part, and

the fifth part not contacting the first pad electrode.

11. (Currently Amended) The circuit board manufacturing method according to ~~claim 1, the forming of the transfer chip including forming an ablation layer between the first substrate and the transfer chip, the ablation layer having a characteristic such that the adhesiveness with respect to the transfer chip is weakened due to a change of state in response to application of energy.~~ claim 3,

the third pad electrode being formed on a second insulating film,

the third pad electrode further having a seventh part at which a thickness of the member is shorter than the thickness of the third part, and

a distance between the second insulating film and the third part being greater than a distance between the second insulating film and the seventh part.

12. (Withdrawn-Currently Amended) A transfer chip serving as a transfer unit manufactured by the method of ~~claim 3.~~ claim 1.

13. (Withdrawn) An electro-optical device manufactured using a circuit board manufactured by the manufacturing method as set forth in claim 1.

14. (Withdrawn) An electronic apparatus, comprising:

the electro-optical device as set forth in claim 13 usable as a display unit.

15. (New) A method for manufacturing an electro-optical device, comprising:

a circuit board manufacturing method according to claim 1.